

Final Product/Process Change Notification Document #: FPCN22244X

Document #: FPCN22244 Issue Date: 12 July 2018

Title of Change:	Qualification of CRM1191A- non-conductive epoxy as die attach material for LM2594DADJR2G.		
Proposed first ship date:	19 October 2018 or earlier after customer approval.		
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>Bob.Sy@onsemi.com></u>		
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Tomas.Vajter@onsemi.com .		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com		
Change Part Identification:	Affected products will be identified with date codes		
Change Category:	☐ Wafer Fab Change		
Change Sub-Category(s): Manufacturing Site Addi Manufacturing Site Trans Manufacturing Process Cl	fer	Datasheet/Product Doc change Shipping/Packaging/Marking Other: Epoxy Change	
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: None	

Description and Purpose:

This Qualification is an Epoxy change replacing conductive (CRM1076WB) to non-conductive epoxy (CRM1191A). Benefit is to eliminate added process of 100% inspection prior WB and to screen out die to lead shorting/epoxy bridging issues (proactive move to prevent risk on potential customer complain in the future).

	Before Change Description	After Change Description
Ероху	Conductive Epoxy-H00144A065 (CRM1076WB)	Non Conductive – H00144A067 (CRM1191A)

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME: LM2594DADJR2G

PACKAGE: SOIC 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 25 °C, 100 % max rated Vcc	1008 hrs	0/320
HTSL	JESD22-A103	Ta= 150 °C	1008 hrs	0/320
TC	JESD22-A104	-65/+150 °C, Air to Air	500 cyc	0/320
HAST	JESD22-A110	TA= +130C, RH = 85%, PSIG= 18.8	96 hrs	0/320
uHAST	JESD22-A118	TA= +130C, RH = 85%, PSIG= 18.8	96 hrs	0/320
PC	J-STD-020 JESD-A113	MSL 1@260°C		0/960

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Electrical Characteristic Summary:		
Electrical characteristics are not impacted.		
List of Affected Parts:		
Part Number	Qualification Vehicle	
LM2594DADJR2G	LM2594DADJR2G	

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Appendix A:	Changed Products		
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stomer Part Number	Qualification Vehicle
	LM2594DADJR2G
15	stomer Part Number